V23990-P630-A44-PM
datasheet

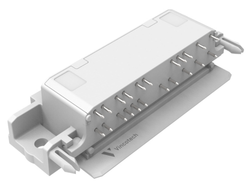
Vincotech

***flow*90PIM 1** — **1200 V / 25 A**

Features

- Trench Fieldstop Technology IGBT4 for low saturation loss
- Supports design with 90° mounting angle between heatsink and PCB
- Clip-in PCB mounting
- Clip or screw on heatsink mounting

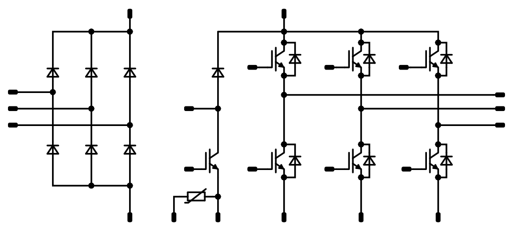
*flow*90 1 housing



Target applications

- Industrial drives

Schematic



Types

- V23990-P630-A44-PM

Copyright Vincotech

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	32	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		75	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	90	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	10	µs
Maximum junction temperature	T_{jmax}			175	°C
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	30	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		50	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	60	W
Maximum junction temperature	T_{jmax}			175	°C
Brake Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	22	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		45	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	65	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	10	µs
Maximum junction temperature	T_{jmax}			175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Brake Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	19	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		20	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	46	W
Maximum junction temperature	T_{jmax}			175	°C
Rectifier Diode					
Peak repetitive reverse voltage	V_{RRM}			1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	33	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, t_p = 10 ms	T_j = 150 °C	200	A
Surge current capability	I^2t			200	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	44	W
Maximum junction temperature	T_{jmax}			150	°C
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
Isolation voltage	V_{isol}	AC Voltage	t_p = 1 min	2500	V
Creepage distance				>12,7	mm
Clearance				11,84	mm
Comparative Tracking Index	CTI			≥ 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,00085	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		25	25 150	1,58	1,96 2,3	2,07(1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			2,4	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		1450		pF
Reverse transfer capacitance	C_{res}							50		pF
Gate charge	Q_g		15		0	25		200		nC
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,05		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	25	25 125 150		126,8 129,6 130		ns
Rise time	t_r					25 125 150		45,2 46,6 46,2		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		239,6 299,6 317,8		ns
Fall time	t_f					25 125 150		68 119,96 135,85		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=2,18 µC Q_{rFWD}=4,01 µC Q_{rFWD}=4,68 µC				25 125 150		2,61 3,53 3,77		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		1,42 2,22 2,45		mWs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Inverter Diode										
Static										
Forward voltage	V_F				25	25 125 150	1,35	1,85 1,83 1,82	2,05[(1)]	V
Reverse leakage current	I_R	V_r = 1200 V				25			5,2	µA
Thermal										
Thermal resistance junction to sink [(2)]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,59		K/W
Dynamic										
Peak recovery current	I_{RRM}	d*i*/d*t*=552 A/µs d*i*/d*t*=488 A/µs d*i*/d*t*=617 A/µs	±15	600	25	25 125 150		12,03 15,13 16,09		A
Reverse recovery time	t_{rr}					25 125 150		345,06 500,67 564,26		ns
Recovered charge	Q_r					25 125 150		2,18 4,01 4,68		µC
Reverse recovered energy	E_{rec}					25 125 150		0,768 1,46 1,74		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		40,38 36,51 35,56		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0005	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 150	1,58	1,89 2,28	2,07[1]	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			2	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		890		pF
Reverse transfer capacitance	C_{res}							30		pF
Gate charge	Q_g		20		0	25		120		nC
Thermal										
Thermal resistance junction to sink [2]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,45		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	15	25 125 150		93,4 96,4 96,8		ns
Rise time	t_r					25 125 150		36,8 37 38,2		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		198,6 255 266,8		ns
Fall time	t_f					25 125 150		80,15 117,59 131,16		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=1,2 µC Q_{rFWD}=2,18 µC Q_{rFWD}=2,49 µC				25 125 150		1,04 1,4 1,49		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		0,855 1,33 1,44		mWs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Brake Diode										
Static										
Forward voltage	V_F				10	25 150	1,35	1,87 1,8	2,05(1)	V
Reverse leakage current	I_R	V_r = 1200 V				25			2,7	µA
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,07		K/W
Dynamic										
Peak recovery current	I_{RRM}	d*i*/d*t*=392 A/µs d*i*/d*t*=326 A/µs d*i*/d*t*=369 A/µs	±15	600	15	25 125 150		7,94 10,27 10,77		A
Reverse recovery time	t_{rr}					25 125 150		317,37 474,79 549,81		ns
Recovered charge	Q_r					25 125 150		1,2 2,18 2,49		µC
Reverse recovered energy	E_{rec}					25 125 150		0,494 0,929 1,08		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		50,61 41,54 39,25		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Rectifier Diode										
Static										
Forward voltage	V_F				8	25 125		0,996 0,907	1,21(1) 1,1(1)	V
Reverse leakage current	I_R	V_r = 1600 V				25			50	µA
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,59		K/W
Thermistor										
Static										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1486 Ω				100	-12		14	%
Power dissipation	P							200		mW
Power dissipation constant	d					25		2		mW/K
B-value	$B_{(25/50)}$	Tol. ±3 %						3950		K
B-value	$B_{(25/100)}$	Tol. ±3 %						3998		K
Vincotech Thermistor Reference									B	

(1) Value at chip level

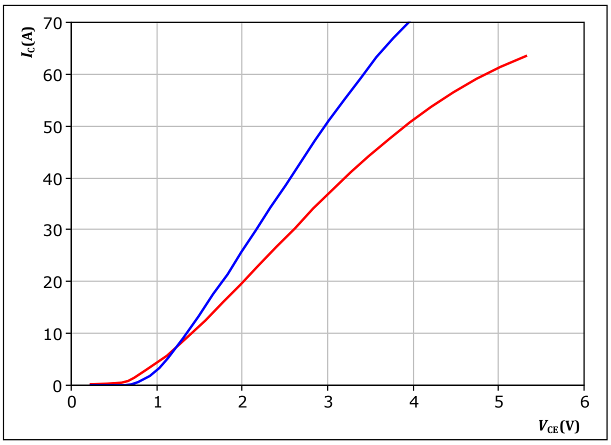
(2) Only valid with pre-applied Vincotech thermal interface material.

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

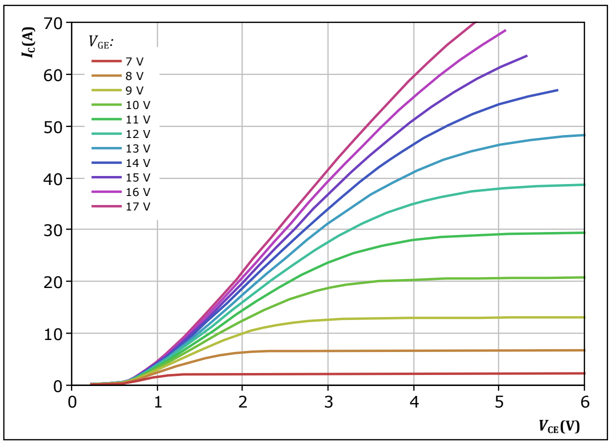


t_p =	250	µs	T_j:	25 °C
V_{GE} =	15	V		150 °C

figure 2. **IGBT**

Typical output characteristics

I_C = f(V_{CE})



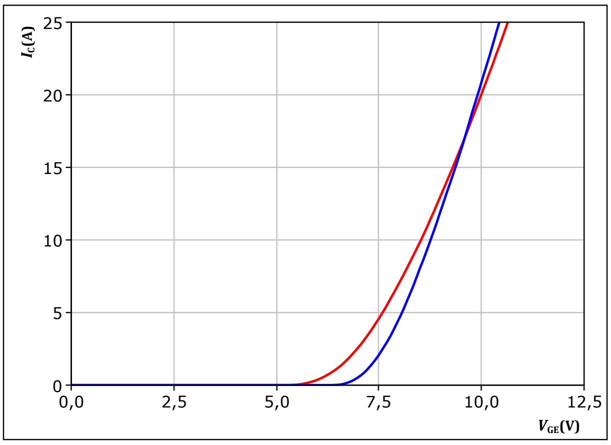
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})

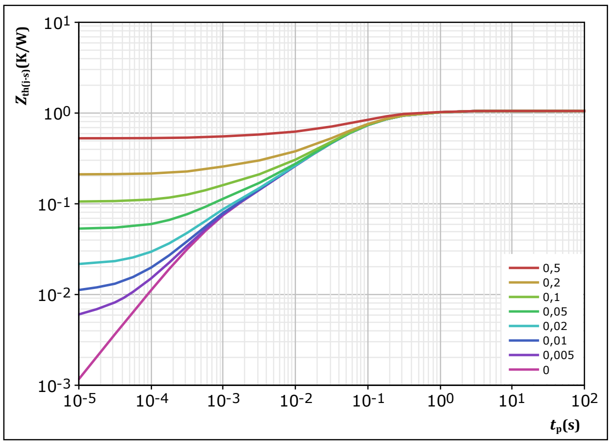


t_p =	250	µs	T_j:	25 °C
V_{CE} =	10	V		150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D =	t_p / T	
$R_{th(j-s)}$ =	1,054	K/W

IGBT thermal model values

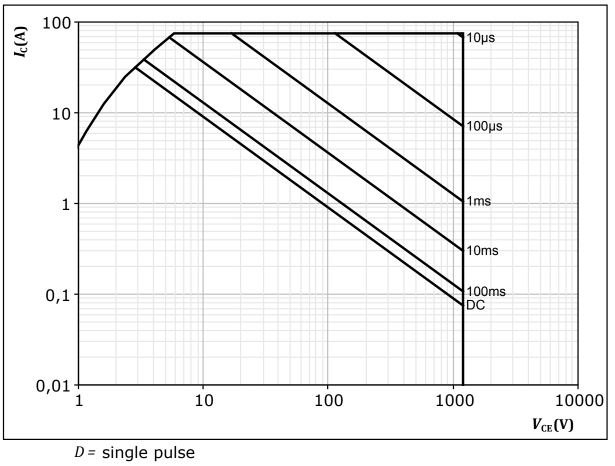
R (K/W)	τ (s)
1,63E-01	6,44E-01
5,75E-01	8,52E-02
1,88E-01	1,87E-02
6,71E-02	5,13E-03
6,12E-02	7,01E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

I_C = f(V_{CE})



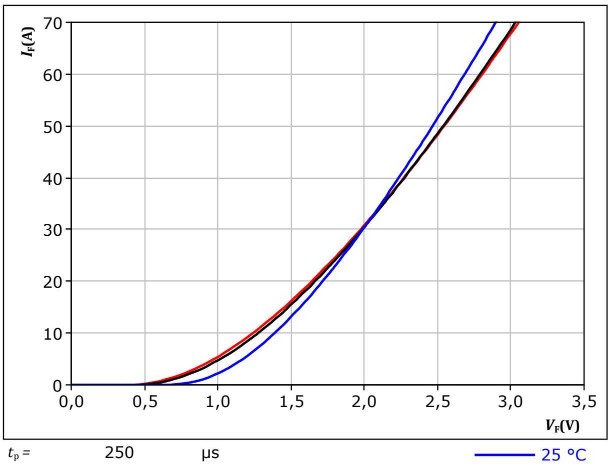
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 6. **FWD**

Typical forward characteristics

I_F = f(V_F)



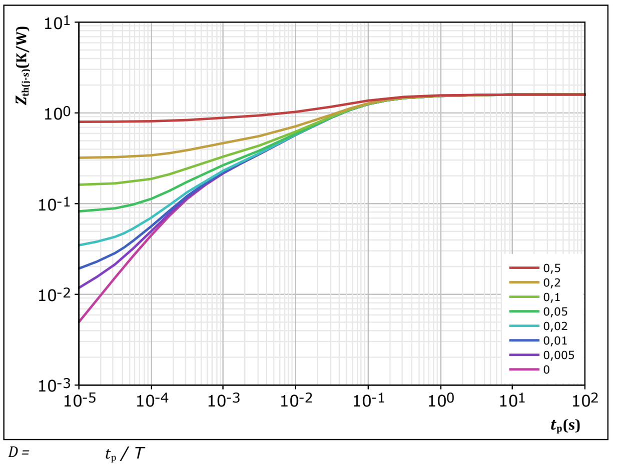
t_p = 250 µs

T_j: 25 °C / 125 °C / 150 °C

figure 7. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 1,594 K/W

FWD thermal model values

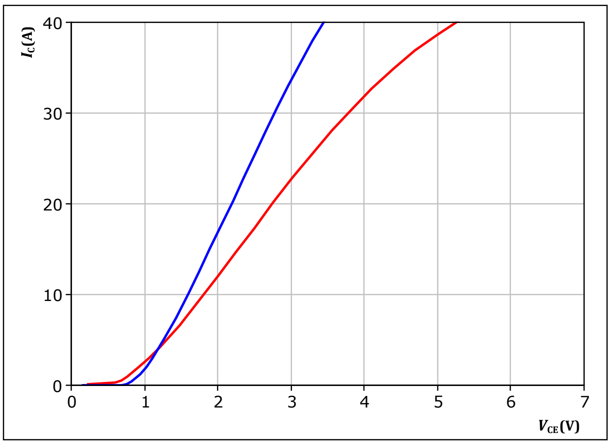
R (K/W)	τ (s)
7,80E-02	2,61E+00
3,11E-01	2,04E-01
6,92E-01	4,64E-02
2,79E-01	8,74E-03
9,99E-02	1,79E-03
1,35E-01	3,39E-04

Brake Switch Characteristics

figure 8. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

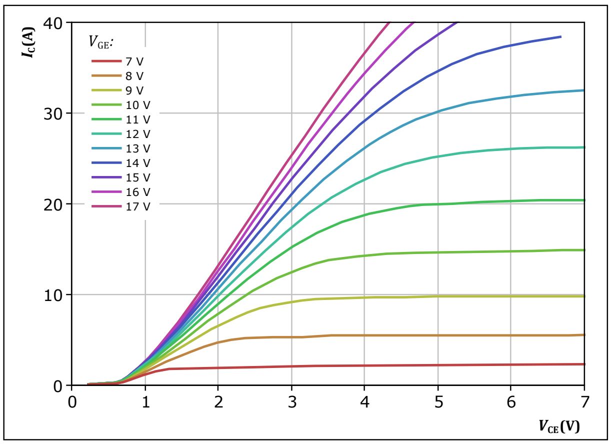


t_p = 250 µs
V_{GE} = 15 V
T_j: 25 °C, 150 °C

figure 9. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

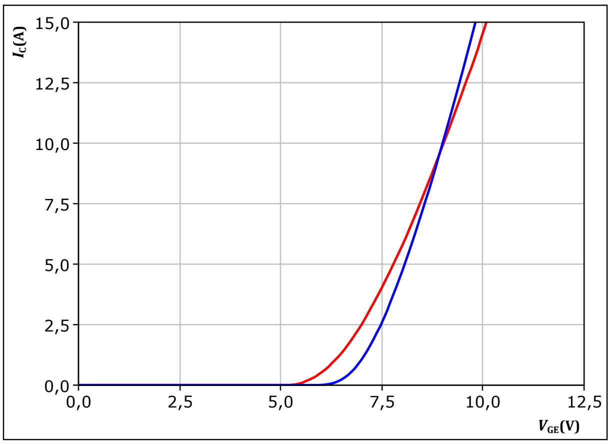


t_p = 250 µs
T_j = 150 °C
V_{GE} from 7 V to 17 V in steps of 1 V

figure 10. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})

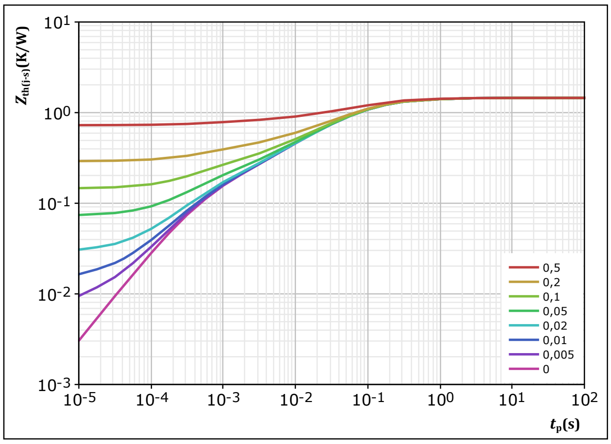


t_p = 250 µs
V_{CE} = 10 V
T_j: 25 °C, 150 °C

figure 11. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T
$R_{th(j-s)}$ = 1,453 K/W

IGBT thermal model values

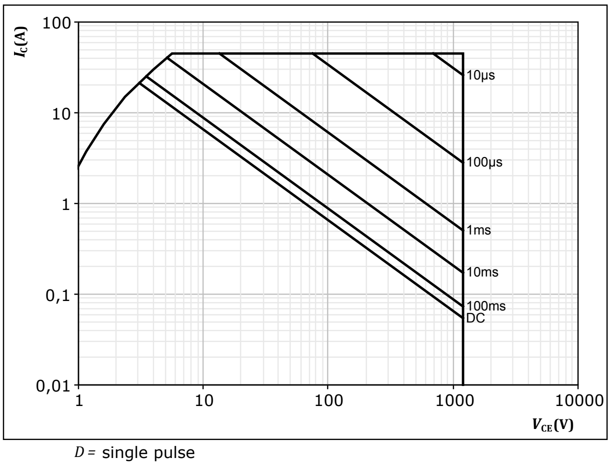
R (K/W)	τ (s)
1,02E-01	1,17E+00
3,31E-01	1,69E-01
5,63E-01	5,65E-02
2,92E-01	1,03E-02
8,13E-02	1,50E-03
8,53E-02	4,00E-04

Brake Switch Characteristics

figure 12. **IGBT**

Safe operating area

I_C = f(V_{CE})



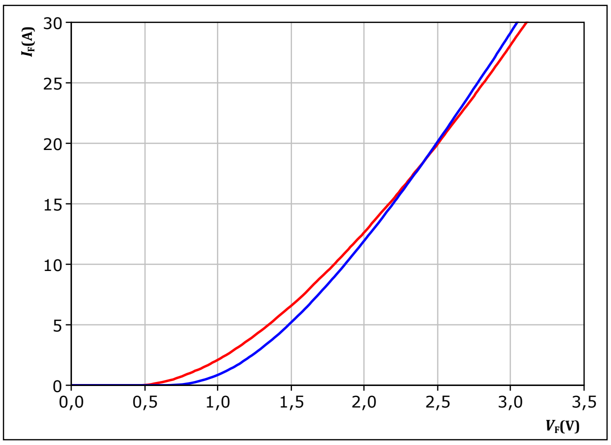
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Brake Diode Characteristics

figure 13. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



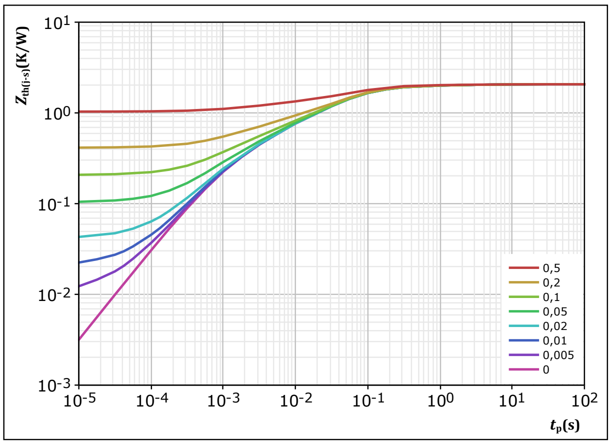
t_p = 250 µs

T_j: 25 °C, 150 °C

figure 14. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 2,066 K/W

FWD thermal model values

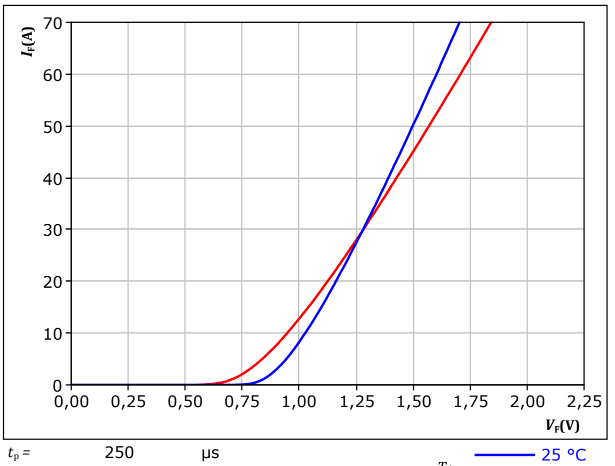
R (K/W)	τ (s)
5,09E-02	4,26E+00
1,55E-01	5,03E-01
7,75E-01	7,89E-02
5,33E-01	2,68E-02
3,54E-01	5,03E-03
1,97E-01	9,09E-04

Rectifier Diode Characteristics

figure 15. **Rectifier**

Typical forward characteristics

$I_F = f(V_F)$



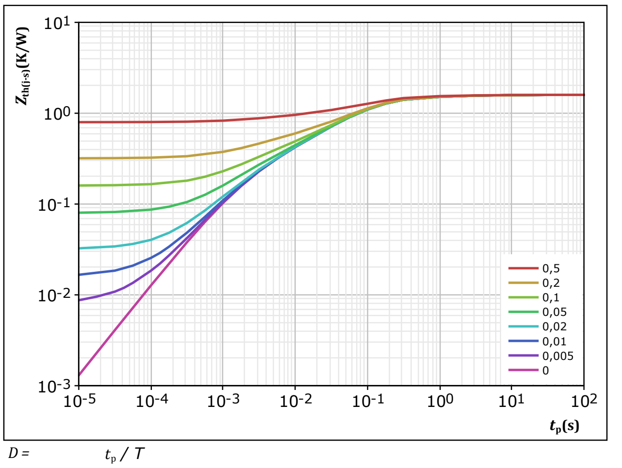
t_p = 250 µs

T_j: 25 °C, 125 °C

figure 16. **Rectifier**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,594 K/W

Rectifier thermal model values

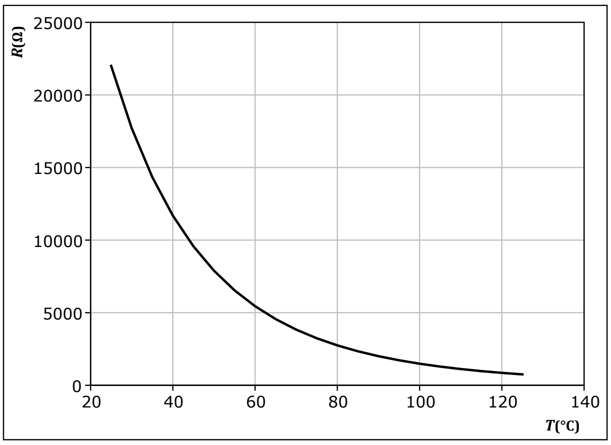
R (K/W)	τ (s)
3,44E-02	9,66E+00
1,12E-01	1,22E+00
5,81E-01	1,45E-01
4,89E-01	5,05E-02
2,38E-01	9,26E-03
1,22E-01	1,79E-03
1,81E-02	7,88E-04

Thermistor Characteristics

figure 17. **Thermistor**

Typical NTC characteristic as function of temperature

R_T = f(T)

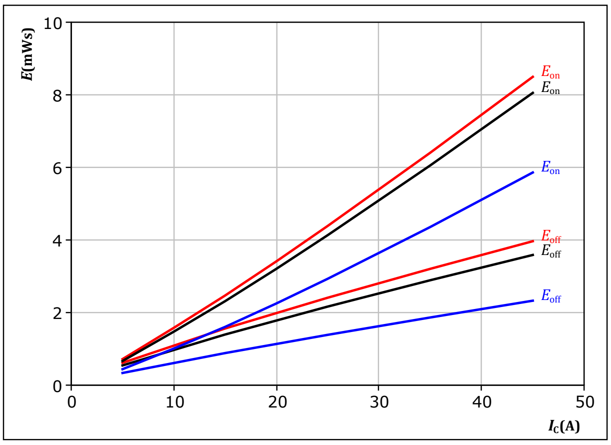


Inverter Switching Characteristics

figure 18. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



With an inductive load at

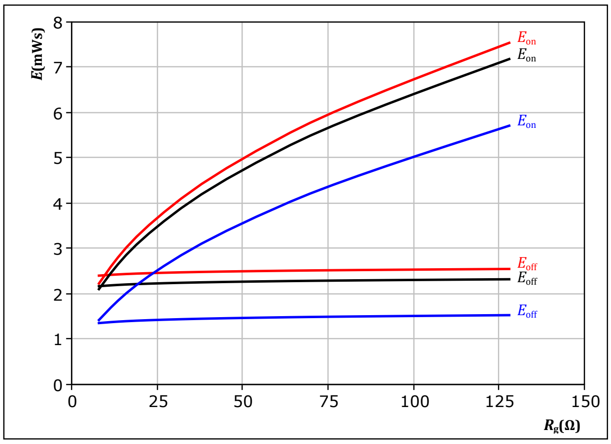
V_{CE} = 600 V
V_{GE} = ±15 V
R_{gon} = 32 Ω
R_{goff} = 32 Ω

T_j: 25 °C, 125 °C, 150 °C

figure 19. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



With an inductive load at

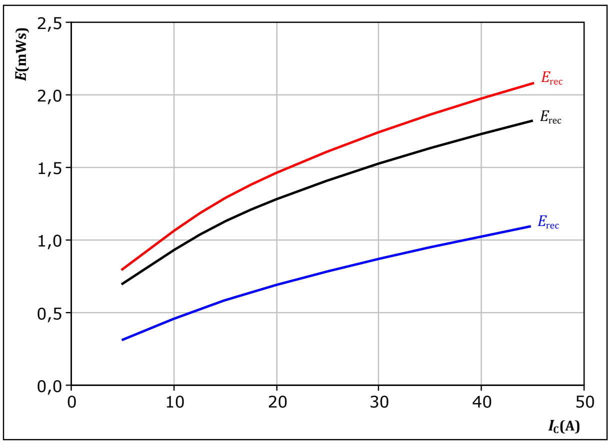
V_{CE} = 600 V
V_{GE} = ±15 V
I_C = 25 A

T_j: 25 °C, 125 °C, 150 °C

figure 20. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



With an inductive load at

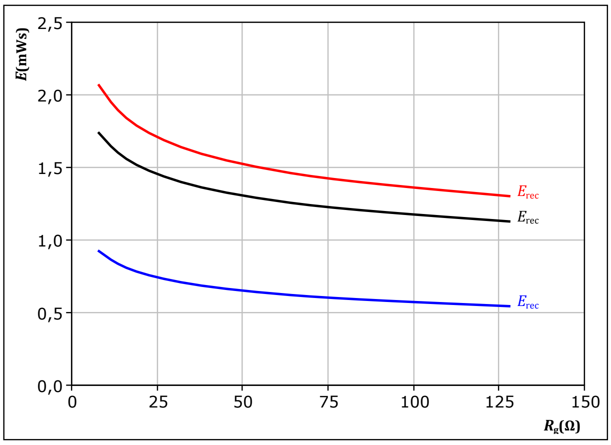
V_{CE} = 600 V
V_{GE} = ±15 V
R_{gon} = 32 Ω

T_j: 25 °C, 125 °C, 150 °C

figure 21. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

V_{CE} = 600 V
V_{GE} = ±15 V
I_C = 25 A

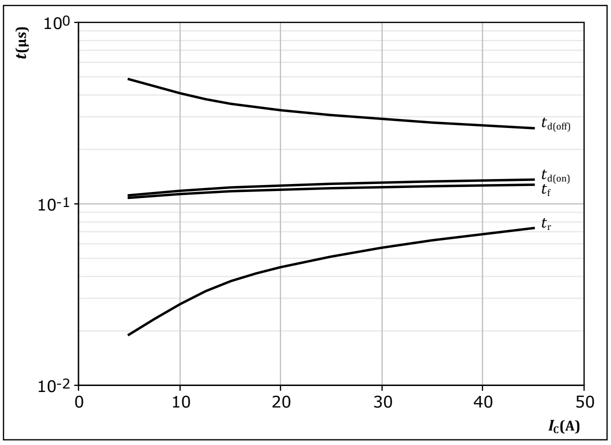
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 22. **IGBT**

Typical switching times as a function of collector current

t = f(I_C)



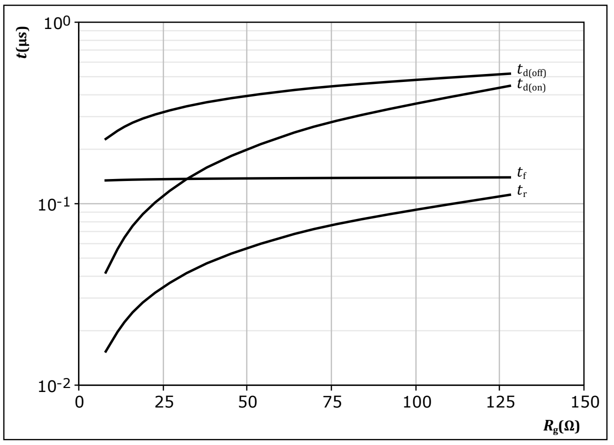
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 23. **IGBT**

Typical switching times as a function of gate resistor

t = f(R_g)



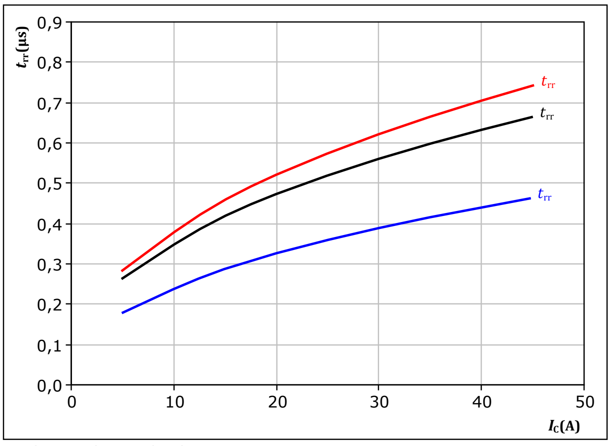
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

figure 24. **FWD**

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



With an inductive load at

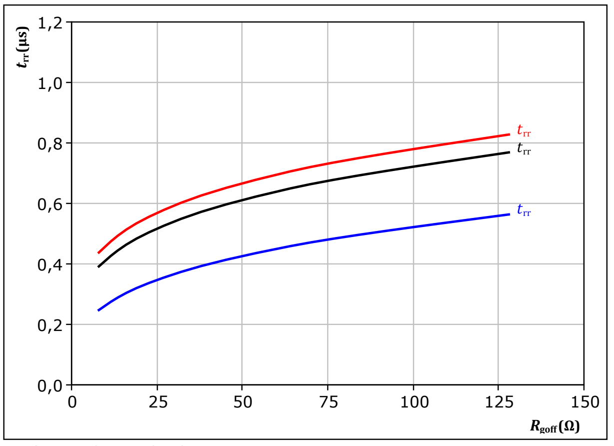
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 25. **FWD**

Typical reverse recovery time as a function of IGBT turn off gate resistor

t_{rr} = f(R_{goff})



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

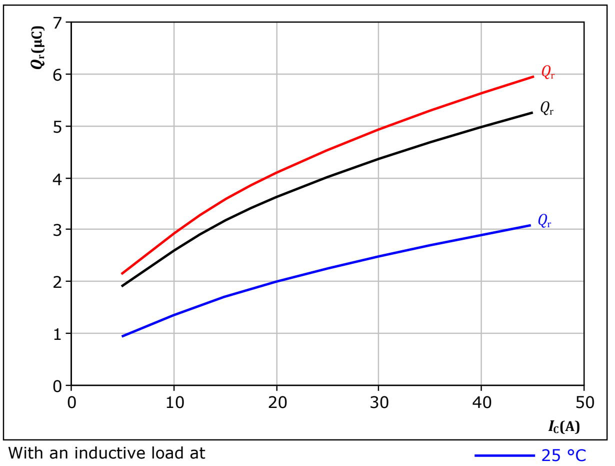
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 26. FWD

Typical recovered charge as a function of collector current

Q_r = f(I_C)



With an inductive load at

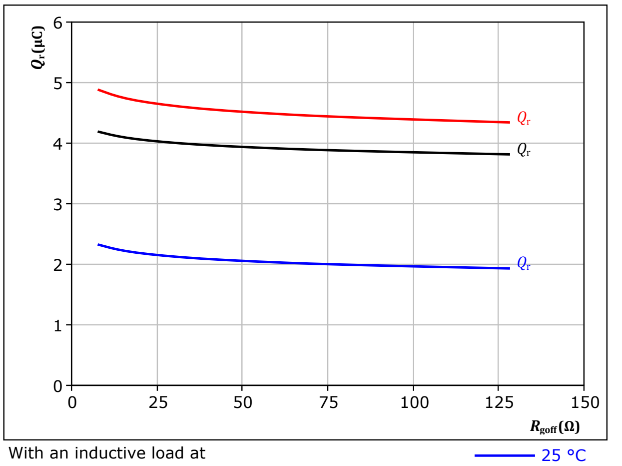
T_j: 25 °C, 125 °C, 150 °C

V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

figure 27. FWD

Typical recovered charge as a function of turn off gate resistor

Q_r = f(R_{goff})



With an inductive load at

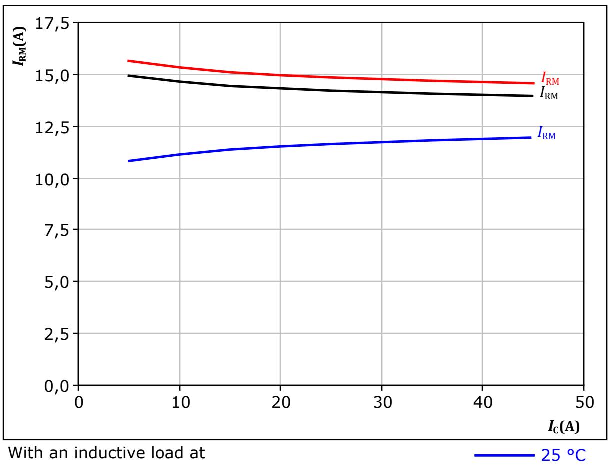
T_j: 25 °C, 125 °C, 150 °C

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

figure 28. FWD

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



With an inductive load at

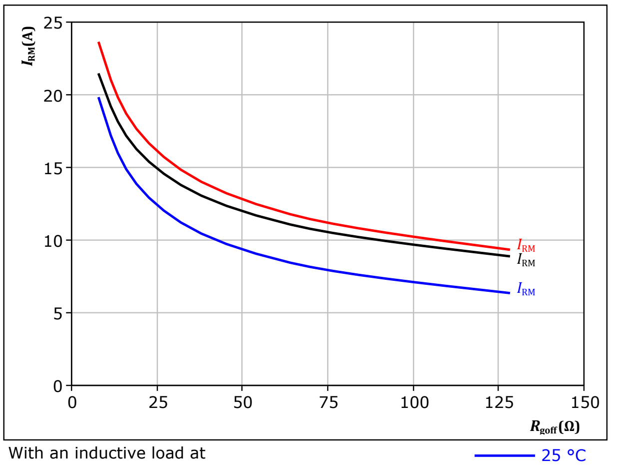
T_j: 25 °C, 125 °C, 150 °C

V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

figure 29. FWD

Typical peak reverse recovery current as a function of turn off gate resistor

I_{RM} = f(R_{goff})



With an inductive load at

T_j: 25 °C, 125 °C, 150 °C

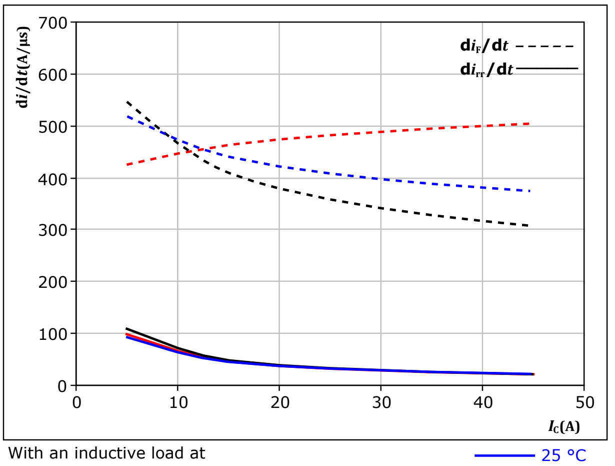
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

Inverter Switching Characteristics

figure 30. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_F/dt,\ di_{rr}/dt = f(I_C)$



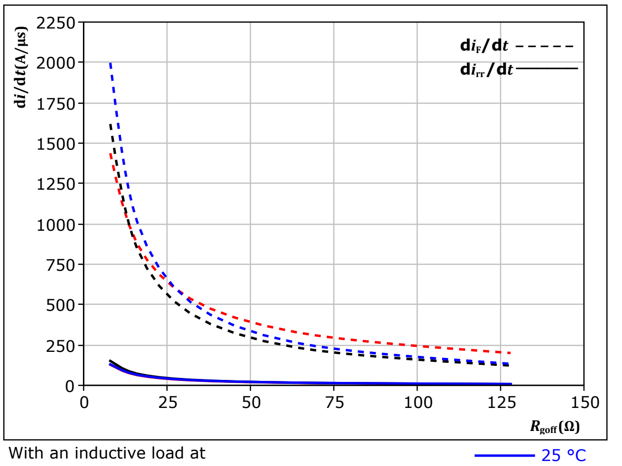
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 31. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn off gate resistor

$di_F/dt,\ di_{rr}/dt = f(R_{goff})$



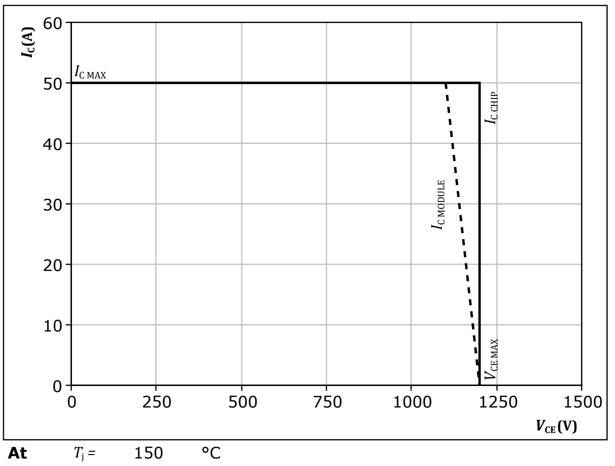
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	25	A		150 °C

figure 32. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



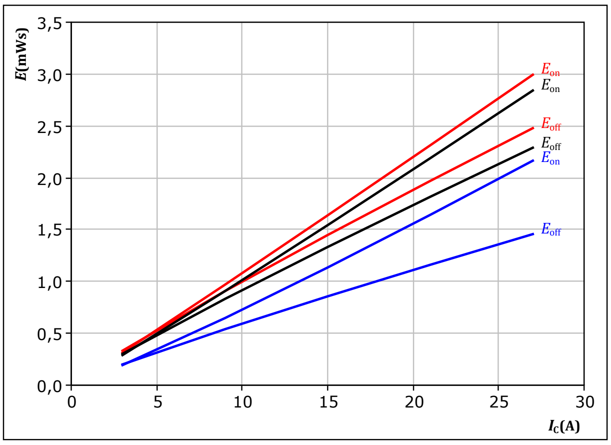
At	T_j =	150	°C
	R_{gon} =	32	Ω
	R_{goff} =	32	Ω

Brake Switching Characteristics

figure 33. **IGBT**

Typical switching energy losses as a function of collector current

E = f(I_C)



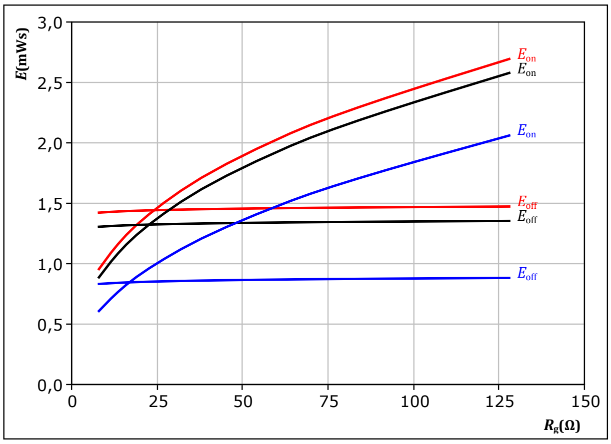
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C
R_{goff} =	32	Ω		

figure 34. **IGBT**

Typical switching energy losses as a function of gate resistor

E = f(R_g)



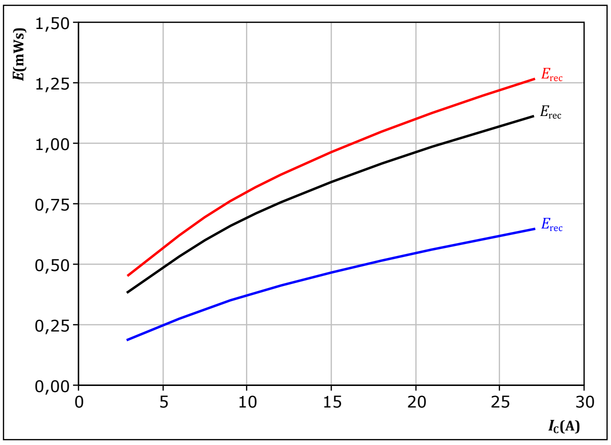
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

figure 35. **FWD**

Typical reverse recovered energy loss as a function of collector current

E_{rec} = f(I_C)



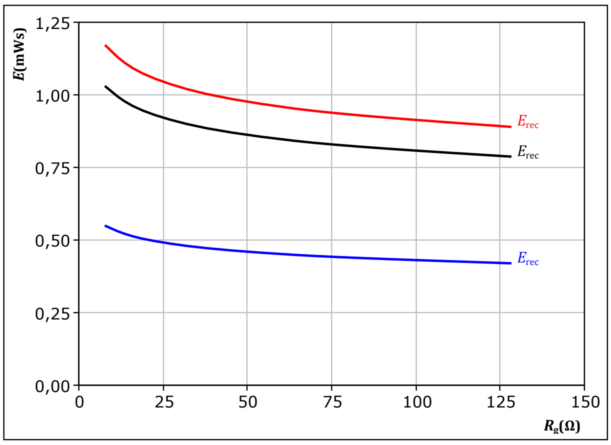
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 36. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

E_{rec} = f(R_g)



With an inductive load at

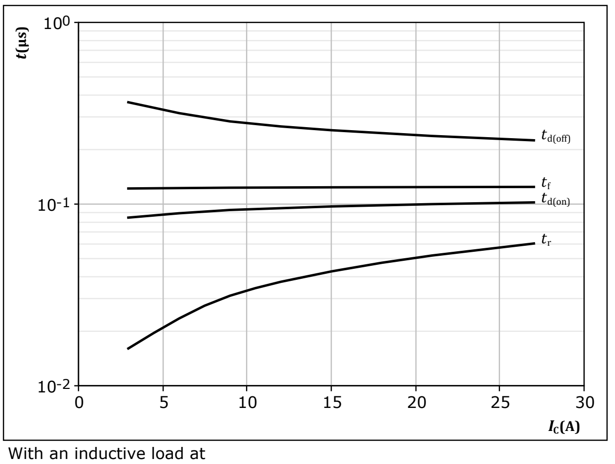
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

Brake Switching Characteristics

figure 37. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



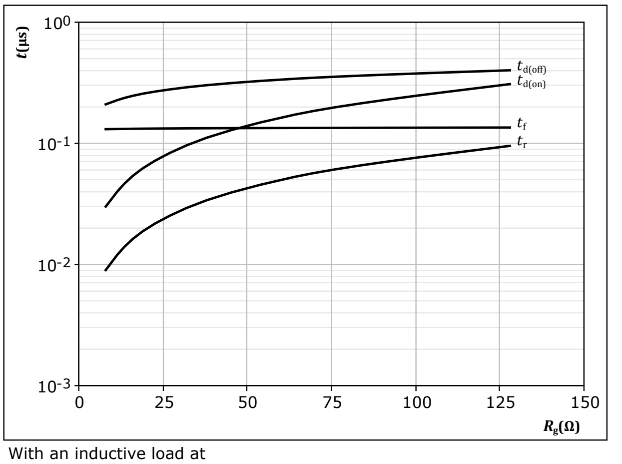
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 38. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



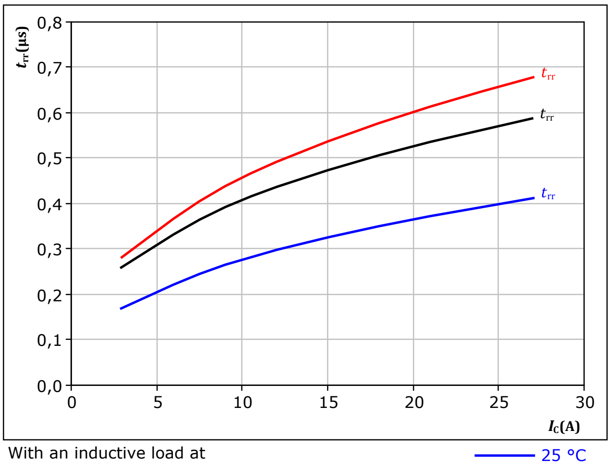
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

figure 39. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



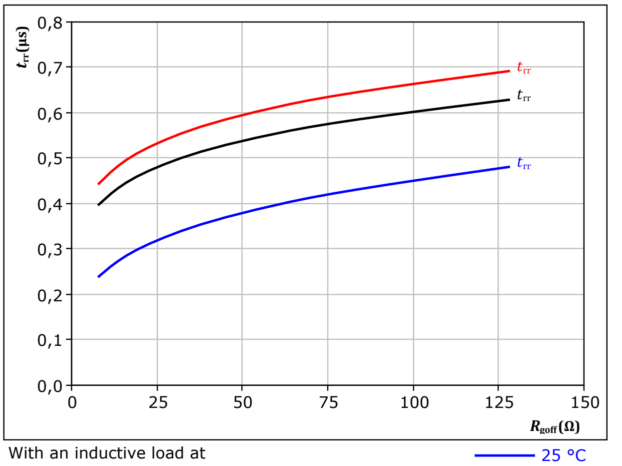
With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

figure 40. **FWD**

Typical reverse recovery time as a function of IGBT turn off gate resistor

$t_{rr} = f(R_{goff})$



With an inductive load at

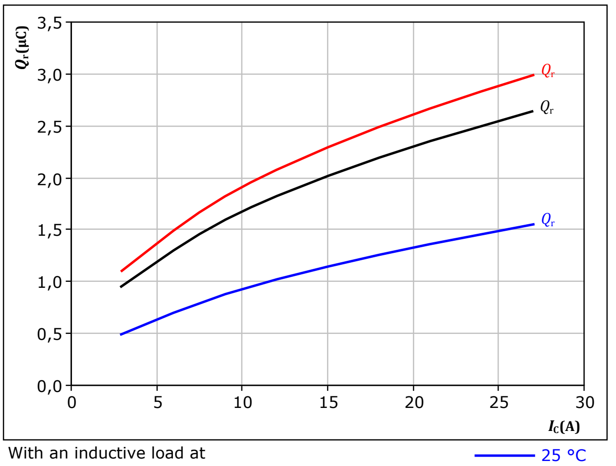
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

Brake Switching Characteristics

figure 41. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



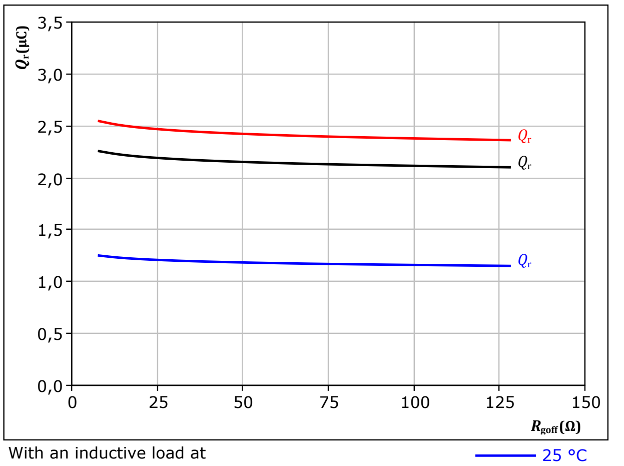
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	±15	V	
R_{gon} =	32	Ω	

figure 42. **FWD**

Typical recovered charge as a function of turn off gate resistor

Q_r = f(R_{goff})



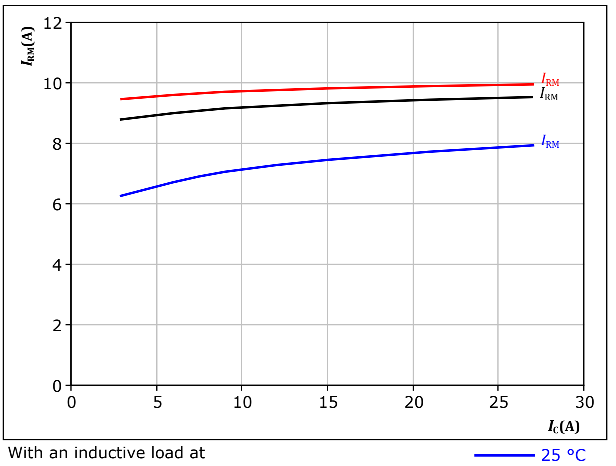
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	±15	V	
I_C =	15	A	

figure 43. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



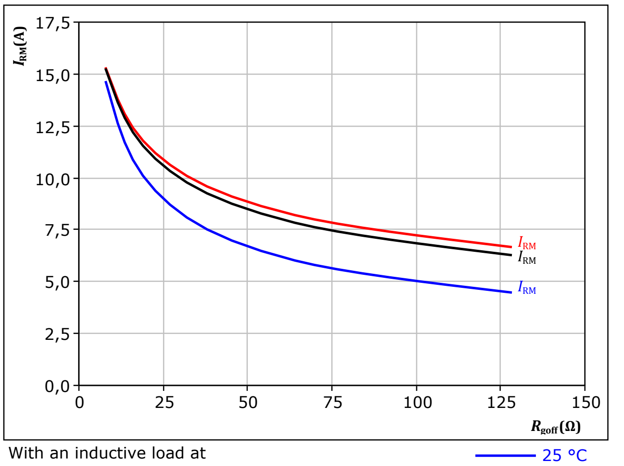
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	±15	V	
R_{gon} =	32	Ω	

figure 44. **FWD**

Typical peak reverse recovery current as a function of turn off gate resistor

I_{RM} = f(R_{goff})



With an inductive load at

V_{CE} =	600	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	±15	V	
I_C =	15	A	

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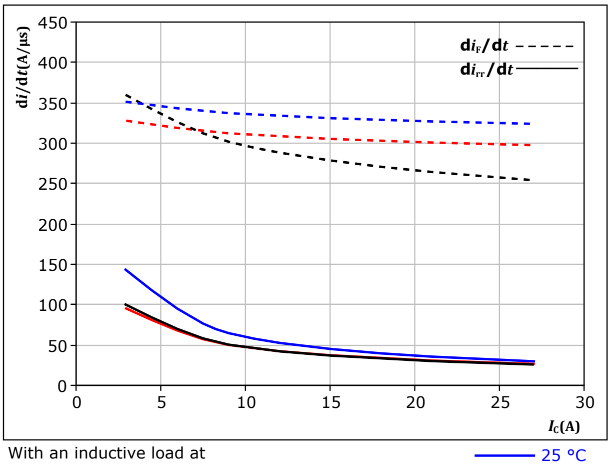
Brake Switching Characteristics

figure 45. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



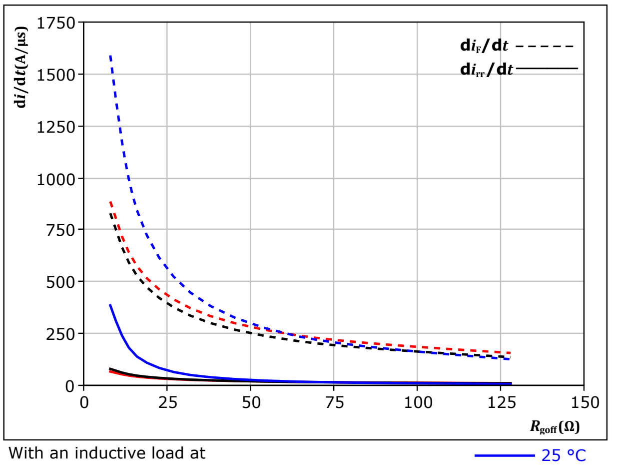
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 46. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn off gate resistor

di_F/dt, di_{rr}/dt = f(R_{goff})



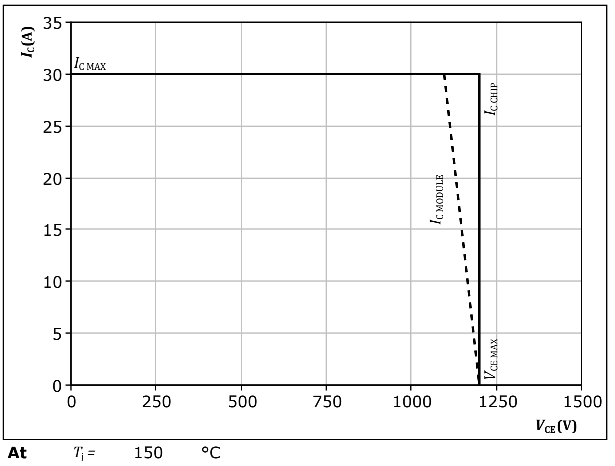
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

figure 47. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At	T_j =	150	°C
	R_{gon} =	32	Ω
	R_{goff} =	32	Ω

Switching Definitions

figure 48.	IGBT

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} = integrating time for E_{off})

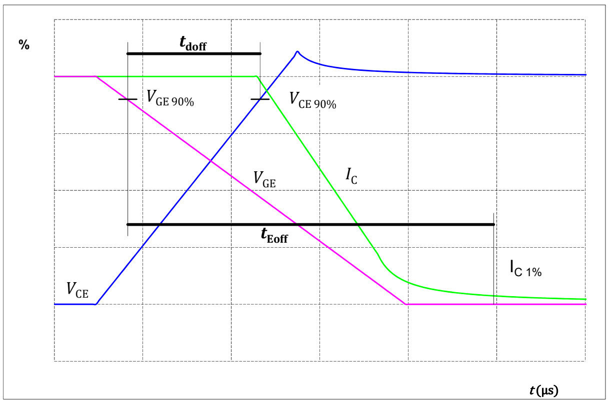


figure 49.	IGBT

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

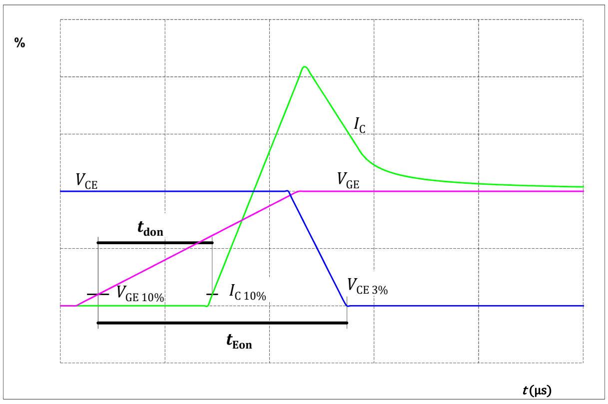


figure 50.	IGBT

Turn-off Switching Waveforms & definition of t_f

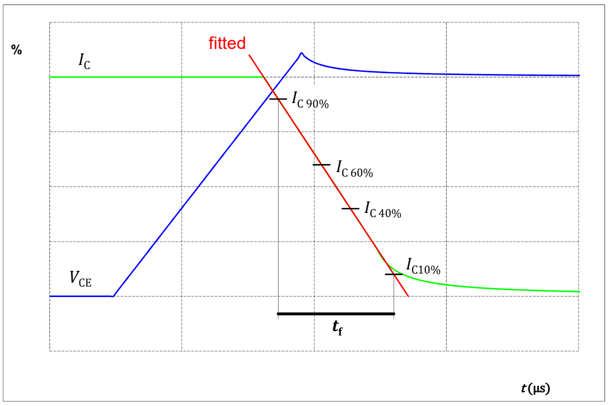
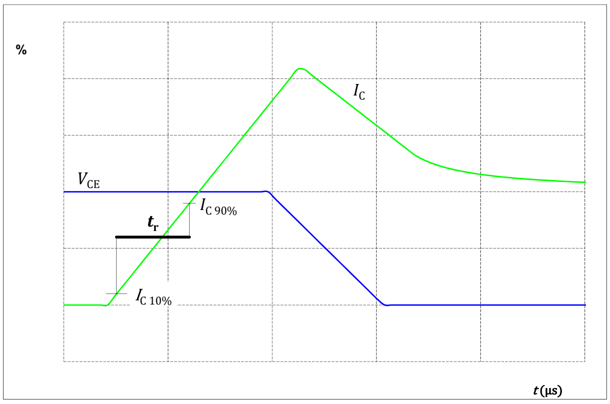


figure 51.	IGBT

Turn-on Switching Waveforms & definition of t_r



Switching Definitions

figure 52. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

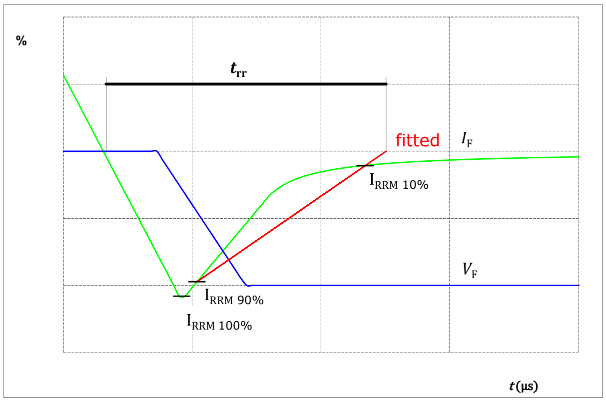
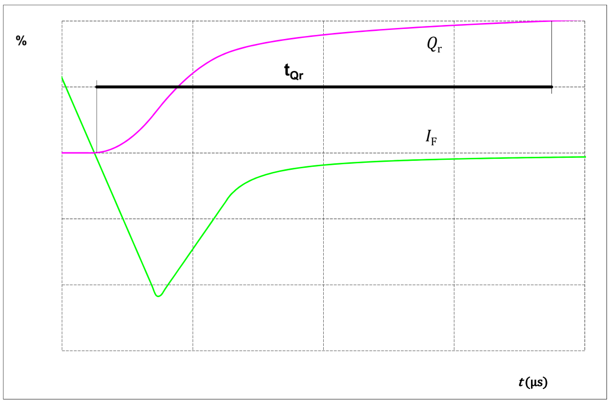


figure 53. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



V23990-P630-A44-PM
datasheet

Ordering Code

Version	Ordering Code
Without thermal paste	V23990-P630-A44-PM
With thermal paste (3,4 W/mK, PSX-P7)	V23990-P630-A44-/3/-PM

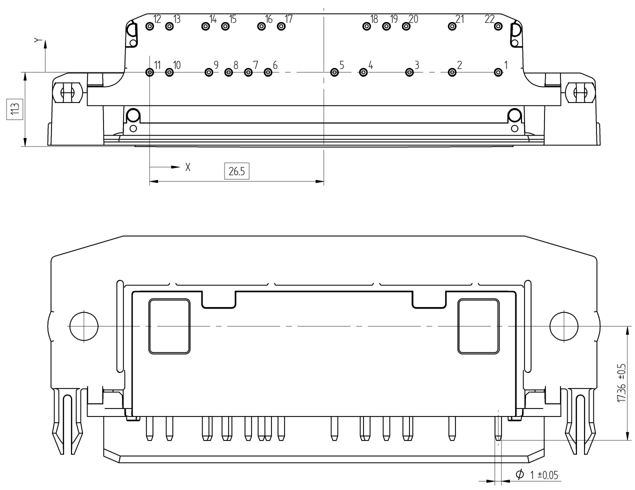
Marking

	**Text**	**VIN**	**Date code**	**Type&Ver**	**UL**	**Lot**	**Serial**
		VIN	WWYY	TTTTTTTVV	UL	LLLLL	SSSS
	Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
		TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

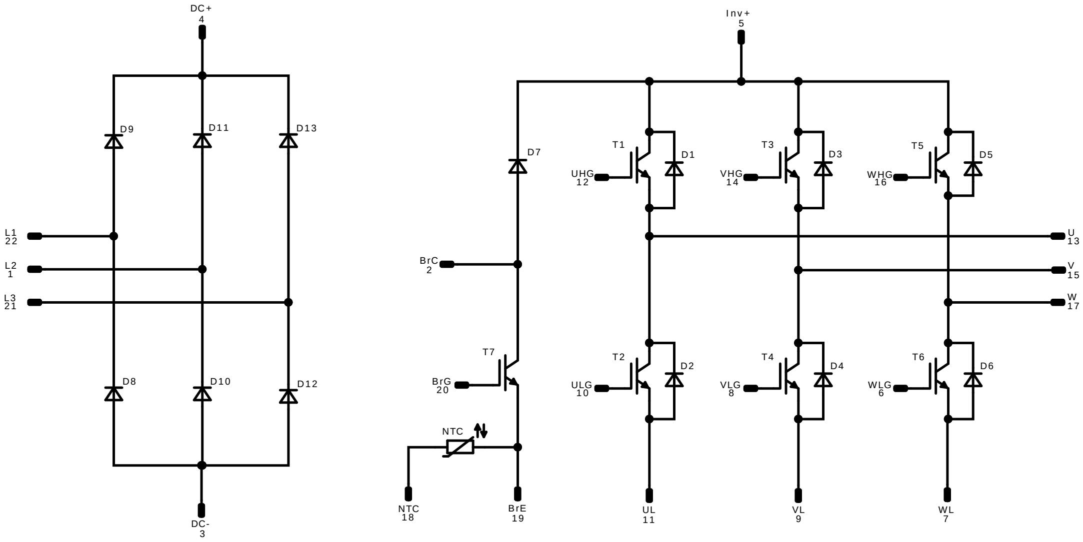
Pin table [mm]

Pin	X	Y	Function
1	53	0	L2
2	46	0	BrC
3	39,5	0	DC-
4	32,5	0	DC+
5	28,1	0	Inv+
6	18	0	WLG
7	15	0	WL
8	12	0	VLG
9	9	0	VL
10	3	0	ULG
11	0	0	UL
12	0	7	UHG
13	3	7	U
14	8,5	7	VHG
15	11,5	7	V
16	17	7	WHG
17	20	7	W
18	33	7	NTC
19	36	7	BrE
20	39	7	BrG
21	46	7	L3
22	53	7	L1



Tolerance of pinpositions: ±0,5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T2, T1, T4, T3, T6, T5	IGBT	1200 V	25 A	Inverter Switch	
D1, D2, D3, D4, D5, D6	FWD	1200 V	25 A	Inverter Diode	
T7	IGBT	1200 V	15 A	Brake Switch	
D7	FWD	1200 V	10 A	Brake Diode	
D8, D9, D10, D11, D12, D13	Rectifier	1600 V	25 A	Rectifier Diode	
NTC	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 80	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow*90 1 packages see vincotech.com website.

Package data
Package data for *flow*90 1 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
V23990-P630-A44-PM-D4-14	9 Jun. 2021	New Datasheet format Update all Rth to PSX thermal interface material Correct Thermistor tolerance	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.